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PATENT ABSTRACTS OF JAPAN

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(71) Applicant: NEC CORP

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(74) Representative:

(54) PRINTED WIRING BOARDS AND METHOD OF MOUNTING BETWEEN THEM

(57) Abstract:

PURPOSE: To simplify the supply of power and GND signals between printed wiring boards, to reduce the number of components, and to be suitable for high density mounting when the printed wiring boards are connected in parallel with spacers between them.

CONSTITUTION: Copper foils 5 that are connected to the same power supply and GND signal layer on the surface of printed wiring boards 1 and 2, that are connected by conductive spacers 3 between them, are exposed and the power supply and the GND signals are supplied between both wiring boards 1 and 2 by fastening both wiring boards 1 and 2 with screws 4 and nuts 11 with spacers 3 between them. The spacers 3 are provided with protrusions 6 on both end surfaces of them to increase contact pressure when they are joined with the printed circuit boards 1 and 2 and the spacers are provided with through holes 12 to pass through the attaching screws 4 at the central part

of them.

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